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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10015691	FILING DATE 12/17/2001	CLASS 228	SUBCLASS 12	GAU 1725	EXAMINER
**APPLICANTS: Terada Touru; Matsumoto Yasuhisa;					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED: JAPAN P.2000-397163 12/27/2000					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no				ATTORNEY DOCKET NO	
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no				067592	
Verified and Acknowledged Examiners's initials					
TITLE : Bonding apparatus				U.S. DEPT. OF COMM/PAT & TM-PTO-436 (Rev. 12-94)	

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Application Examiner	
		PREPARED FOR ISSUE	
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